SOLDERING CONDITIONS 焊接條件

☐ For Chip Type Aluminum Electrolytic Capacitors 適用於貼片式鋁電解電容器

- Radial lead type aluminum electrolytic capacitors please see titled “Mounting” in “General Information for Application”.
- 插件式鋁電解電容器請查閱“鋁電解電容器使用注意事項”裡的“安裝”說明。

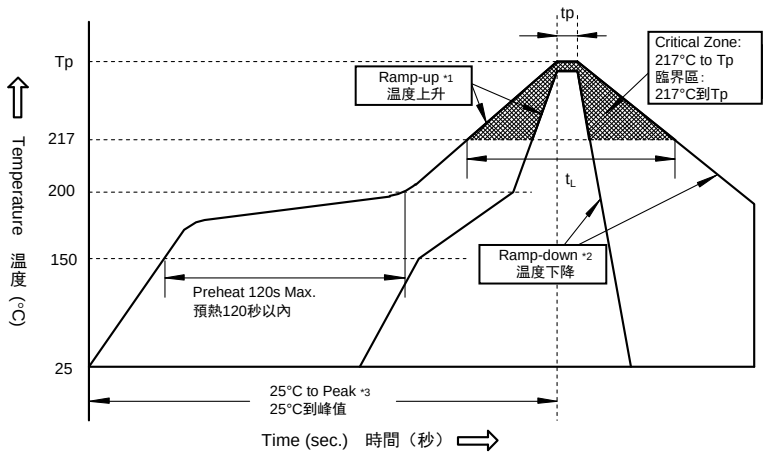
■ Recommended Conditions for Reflow Soldering 推薦回流焊條件

(1) A thermal condition system such as infrared radiation (IR) or hot blast should be adopted, and vapor heat transfer systems (VPS) are not recommended.
應採用紅外線或熱風回流焊接，而不宜採用汽相加熱回流焊接。

(2) Reflow soldering should be within 2 cycles. Please make sure that the parts have enough cooling time between the first and second soldering process.
回流焊次數最多 2 次，請確保在第 1 次和第 2 次之間產品有足夠的冷卻時間。

(3)
- The time of preheating from 150°C to 180°C shall be within maximum 120 seconds;
從 150°C 到 180°C 的預熱時間應在 120 秒以內；
- The time of soldering temperature at 217°C measured on capacitors' top shall not exceed t_L (second);
電容器頂部溫度超過 217°C 的焊接時間不得超過 t_L（秒）；
- The peak temperature on capacitors' top shall not exceed Tp(°C), and the time within 5°C of actual peak temperature shall not exceed tp (second).
電容器頂部的峰值溫度不得超過 Tp(°C)，在 5°C 範圍內的實際峰值溫度時間不得超過 tp（秒）。

■ Classification Reflow Profile 回流焊曲線圖



*1. Average ramp-up rate is 3°C/second Max.
*2. Ramp-down rate is 6°C /second Max.
*3. Time from 25°C to peak temperature is 6 minutes Max.

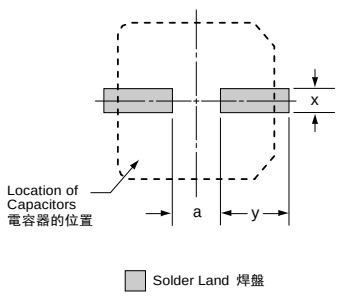
*1. 溫度上升平均每秒鐘最多 3°C；
*2. 溫度下降平均每秒鐘最多 6°C；
*3. 從 25°C 上升到峰值溫度的時間最多 6 分鐘。

■ Classified at Temperature and Time 溫度和時間分類

Size 尺寸	Preheat 預熱	Tp (°C)	t_L (second 秒)	tp (second 秒)	Reflow number 回流焊次數
∅4~∅6.3	150~180°C 120s Max. (120 秒以內)	255	60	5	2 times or less 最多 2 次
∅8×6.7/7.7/9		255	60	5	
∅8×10/10.5/12		250	60	5	
∅10		245	60	5	

- Please contact us if your condition is over the maximum. ● 如使用條件超出最大值，請與我們聯繫。

■ Recommended Solder Land Size on PC Board 推薦安裝尺寸 (Unit: mm)



Size 尺寸	a	y	x
∅4	1.0	2.6	1.6
∅5	1.4	3.0	1.6
∅6.3	1.9	3.5	1.6
∅8 × 6.2	2.1	4.0	1.6
∅8 × 10.5	3.0	3.5	2.5
∅10	4.0	4.0	2.5